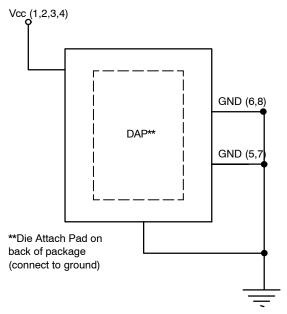
NSPU5132

13.5 V Unidirectional ESD and Surge Protection Device

Features

- Unidirectional High Voltage ESD & Surge Protection Device
- Provides ESD Protection to IEC61000-4-2 Level 4: ±30 kV Contact Discharge
- Small Package (1.8 mm x 2.0 mm)
- High Voltage Zener Diode Protects Supply Rail up to 200 A (8/20 μs)
- These Devices are Pb-Free and are RoHS Compliant

APPLICATION DIAGRAM





ON Semiconductor®

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UDFN6 D4 SUFFIX CASE 517CS

BLOCK DIAGRAM



MARKING DIAGRAM



4W = Specific Device Code

M = Date Code

= Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
NSPU5132MUTBG	UDFN6 3000 / Tape (Pb-Free) Reel	
	(1 b-1 100)	TICCI

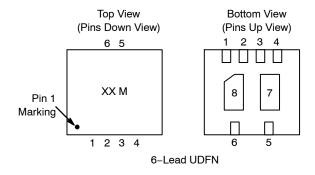
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NSPU5132

Table 1. PIN DESCRIPTIONS

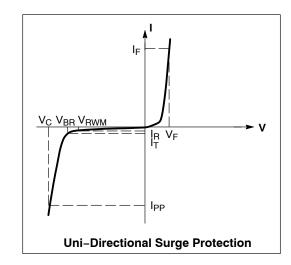
	6-Lead, UDFN-8 Package					
Pin	Name	Description				
1	V _{CC}	Cathode				
2	V _{CC}	Cathode				
3	V _{CC}	Cathode				
4	V _{CC}	Cathode				
5	GND	Anode				
6	GND	Anode				
7	GND	Anode				
8	GND	Anode				

PACKAGE / PINOUT DIAGRAMS



ELECTRICAL CHARACTERISTICS

Symbol	Parameter				
I _{PP}	Maximum Reverse Peak Pulse Current				
V _C	Clamping Voltage @ I _{PP}				
V _{RWM}	Working Peak Reverse Voltage				
I _R	Maximum Reverse Leakage Current @ V _{RWM}				
V _{BR}	Breakdown Voltage @ I _T				
I _T	Test Current				
ΘV _{BR}	Maximum Temperature Coefficient of V _{BR}				
I _F	Forward Current				
V _F	Forward Voltage @ I _F				



SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Operating Temperature Range	-55 to +125	°C
Storage Temperature Range	-65 to +150	°C
Peak Current (t _p = 8/20 μs)	200	Α
Peak Pulse Power (t _p = 8/20 μs)	4800	W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS

		V _{RWM} (V)	I _R @ V _{RWM}	Breakdown Voltage			V _C @ (8 x 20 μs		Junction C (V _R = 0 V, Pin 1 to	f = 1 MHz,	
Device	Device	(Note 1)	(μ A)	V _{BR} V (Note 2) @ I _T (m/		@ I _T (mA)	V _C (V)	I _{PP} (A)	C ^J (pF)	
Name	Marking	Max	Max	Min	Nom	Max		Max		Тур	Max
NSPU5132	4W	13.5	0.5	13.6	15.5	17.5	1	24	200	1325	1550

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 1. A surge protector is normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal to or greater than the DC or continuous peak operating voltage level.
- 2. V_{BR} measured at pulse test current I_T at an ambient temperature of 25°C.
- 3. Surge current waveform per Figure 1.

NSPU5132

TYPICAL CHARACTERISTICS

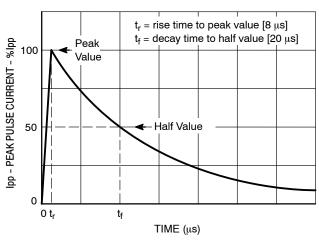


Figure 1. IEC61000-4-5 8/20 μs Pulse Waveform

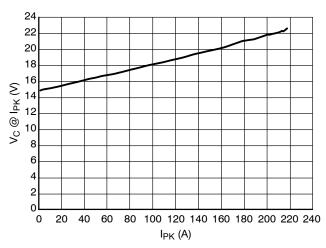
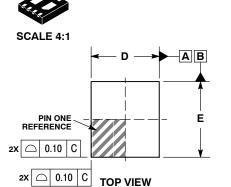
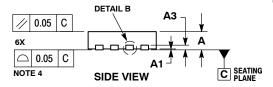


Figure 2. Positive Clamping Voltage vs. Peak Pulse Current

DATE 30 APR 2013





DETAIL A

e1/2

2X D2-

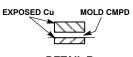
0.10 C

△ 0.10 C

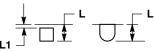
e1

BOTTOM VIEW

UDFN6, 1.8x2, 0.4P CASE 517CS **ISSUE 0**

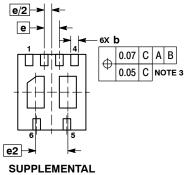


DETAIL B ALTERNATE CONSTRUCTION



ALTERNATE CONSTRUCTIONS





BOTTOM VIEW

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- 714.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION 6 APPLIES TO PLATED TERMINALS
 AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED PAD
- AS WELL AS THE TERMINALS.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00 0.05					
A3	0.125 REF					
b	0.15 0.25					
D	1.80 BSC					
D2	0.35	0.55				
E	2.00 BSC					
E2	0.74 0.94					
е	0.40 BSC					
e1	0.80 BSC					
e2	0.95 BSC					
L	0.20	0.40				
L1	0.15					

GENERIC MARKING DIAGRAM*

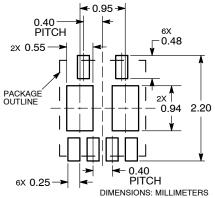


XX = Specific Device Code

= Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	UDFN6 1.8X2, 0.4P		PAGE 1 OF 1		

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